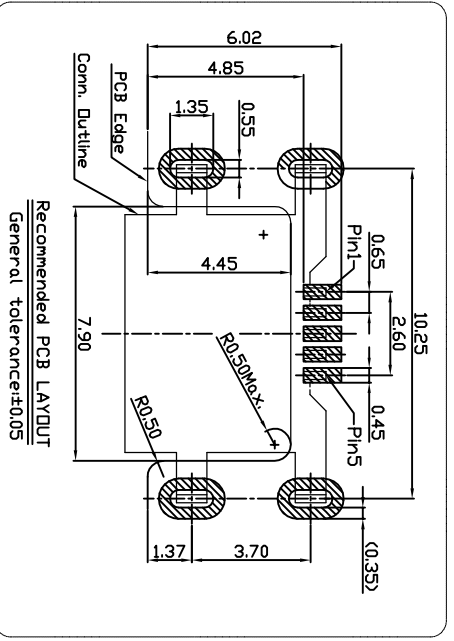
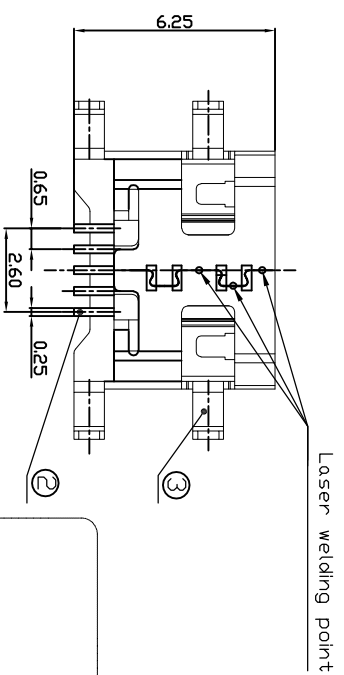
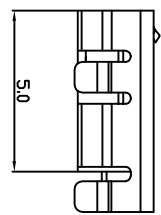
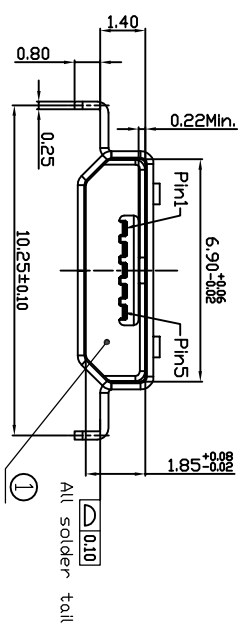
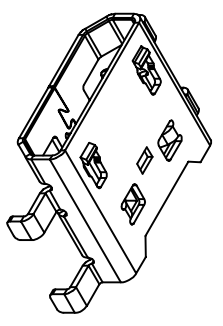
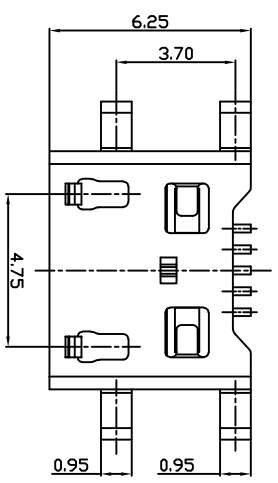


REV.	ECH. NO.	APPD.
A	EXXXXXXXXXX	Yongguifeng



Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy, t=0.20mm
- 1.3 Shell: copper alloy, t=0.25mm

2. Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mΩ Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 1000 insertion/extraction cycles
- 2.7 Temperature range: -30. C~80. C

U447-011X-XXXXX8

- 1: 铁壳镀镍
- 5: 铜壳镀镍
- 6: 铜壳镀雾锡
- 1: 半金1u"
- 3: 半金3u"
- 5: 半金5u"
- G: 半金G/Fu"
- 9: 镀全金1u"
- 4: 镀全亮锡
- 1: PA66
- 2: PBT
- 6: LCP
- 1: 吸塑盒
- 2: 吸塑管
- 3: 裁带
- 6: 裁带+贴麦拉
- 1: 黑色
- 2: 白色
- 3: 米黄色

TOLERANCE UNLESS OTHERWISE SPECIFIED		HW 深圳市华联威电子科技有限公司	
XXX ±0.10	XX ±0.20	X ±0.30	XX ±2
HUA LIAN WEI TECHNOLOGY ELECTRONICS CO.,LTD.		PART NAME: MICRO 5P 四脚沉板0.8	
APPROVED		PART No:	U447-0116-061038
CHECKED		PROJECTION:	
DRAWN	Yongguifeng	UNIT:	mm
DATE	2021.12.01	SCALE	1:1
		SHEET	1 OF 1
		REV.	A